

What is claimed is:

1. An electronic circuit device comprising:
 - an electronic component having a connection terminal on one side thereof;
 - 5 a circuit board;
 - an adhesive sheet having a through-hole; and
 - a conductive adhesive provided in said through-hole;wherein said electronic component and said circuit board are bonded to each other via said adhesive sheet, and said connection terminal on said electronic component and an electrode pad on said circuit board are bonded to each other by said conductive adhesive in said through-hole.
- 10 2. The electronic circuit device according to claim 1, wherein at least one of said connection terminal and said electrode pad protrude into said through-hole.
3. The electronic circuit device according to claim 1, wherein said circuit board comprises a polymeric resin sheet.
- 20 4. The electronic circuit device according to claim 3, wherein said polymeric resin sheet is made of a material selected from the group consisting of polyethylene terephthalate, acrylnitrile-butadiene-styrene, polycarbonate, and polyimide.
- 25 5. The electronic circuit device according to claim 1, wherein said conductive adhesive is a conductive paste consisting essentially of conductive particles and a thermosetting resin binder.

6. The electronic circuit device according to claim 1, wherein said adhesive sheet is one of a thermosetting resin sheet and a thermoplastic resin sheet.

5 7. The electronic circuit device according to claim 1, wherein said conductive adhesive essentially consists of conductive particles and a thermosetting resin binder, and said adhesive sheet includes a thermosetting resin, with said thermosetting resin being such that it begins to cure at a lower temperature than does said thermosetting resin binder.

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8. A method of manufacturing an electronic circuit device, comprising:

 bonding an adhesive sheet to a circuit board so that a through-hole, through said adhesive sheet, is aligned with an electrode pad provided on a surface of said circuit board;

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 providing a conductive adhesive in said through-hole; and

 bonding a connection terminal, provided on one side of an electronic component, to said electrode pad on said circuit board via said conductive adhesive in said through-hole, and bonding said electronic component to said adhesive sheet.

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9. The method according to claim 8, wherein said adhesive sheet is one of a thermosetting resin sheet and a thermoplastic resin sheet.

25 10. The method according to claim 8, wherein said conductive adhesive consists essentially of conductive particles and a thermosetting resin binder, and said adhesive sheet includes a thermosetting resin, with said thermosetting resin being such that it begins to cure at a lower temperature than does said thermosetting resin binder.